



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

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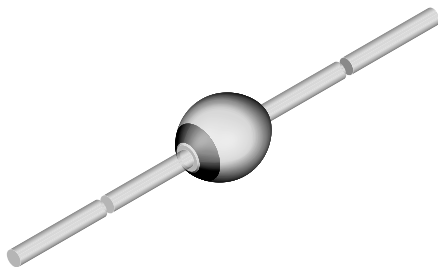
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Fast Avalanche Sinterglass Diode



949539

FEATURES

- Glass passivated junction
- Hermetically sealed package
- Low reverse current
- Soft recovery characteristics
- Material categorization:
For definitions of compliance please see www.vishay.com/doc?999912



RoHS
COMPLIANT
HALOGEN
FREE

APPLICATIONS

- Fast rectification and switching diode

MECHANICAL DATA

Case: SOD-57

Terminals: plated axial leads, solderable per MIL-STD-750, method 2026

Polarity: color band denotes cathode end

Mounting position: any

Weight: approx. 369 mg

ORDERING INFORMATION (Example)

DEVICE NAME	ORDERING CODE	TAPED UNITS	MINIMUM ORDER QUANTITY
BYT52M	BYT52M-TR	5000 per 10" tape and reel	25 000
BYT52M	BYT52M-TAP	5000 per ammpack	25 000

PARTS TABLE

PART	TYPE DIFFERENTIATION	PACKAGE
BYT52A	$V_R = 50\text{ V}$; $I_{F(AV)} = 1.4\text{ A}$	SOD-57
BYT52B	$V_R = 100\text{ V}$; $I_{F(AV)} = 1.4\text{ A}$	SOD-57
BYT52D	$V_R = 200\text{ V}$; $I_{F(AV)} = 1.4\text{ A}$	SOD-57
BYT52G	$V_R = 400\text{ V}$; $I_{F(AV)} = 1.4\text{ A}$	SOD-57
BYT52J	$V_R = 600\text{ V}$; $I_{F(AV)} = 1.4\text{ A}$	SOD-57
BYT52K	$V_R = 800\text{ V}$; $I_{F(AV)} = 1.4\text{ A}$	SOD-57
BYT52M	$V_R = 1000\text{ V}$; $I_{F(AV)} = 1.4\text{ A}$	SOD-57

ABSOLUTE MAXIMUM RATINGS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)

PARAMETER	TEST CONDITION	PART	SYMBOL	VALUE	UNIT
Reverse voltage = repetitive peak reverse voltage	See electrical characteristics	BYT52A	$V_R = V_{RRM}$	50	V
		BYT52B	$V_R = V_{RRM}$	100	V
		BYT52D	$V_R = V_{RRM}$	200	V
		BYT52G	$V_R = V_{RRM}$	400	V
		BYT52J	$V_R = V_{RRM}$	600	V
		BYT52K	$V_R = V_{RRM}$	800	V
		BYT52M	$V_R = V_{RRM}$	1000	V
Peak forward surge current	$t_p = 10\text{ ms}$, half sine wave		I_{FSM}	50	A
Average forward current	On PC board		$I_{F(AV)}$	0.85	A
	$l = 10\text{ mm}$		$I_{F(AV)}$	1.4	A
Non repetitive reverse avalanche energy	$I_{(BR)R} = 0.4\text{ A}$	BYT52J	E_R	10	mJ
		BYT52K	E_R	10	mJ
		BYT52M	E_R	10	mJ
Junction and storage temperature range			$T_j = T_{stg}$	- 55 to + 175	$^{\circ}\text{C}$



MAXIMUM THERMAL RESISTANCE ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)

PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Junction ambient	Lead length $l = 10\text{ mm}$, $T_L = \text{constant}$	R_{thJA}	45	K/W
	On PC board with spacing 25 mm	R_{thJA}	100	K/W

ELECTRICAL CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)

PARAMETER	TEST CONDITION	PART	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	$I_F = 1\text{ A}$		V_F	-	-	1.3	V
Reverse current	$V_R = V_{RRM}$		I_R	-	-	5	μA
	$V_R = V_{RRM}$, $T_J = 150\text{ }^{\circ}\text{C}$		I_R	-	-	150	μA
Reverse recovery time	$I_F = 0.5\text{ A}$, $I_R = 1\text{ A}$, $i_R = 0.25\text{ A}$		t_{rr}	-	-	200	ns

TYPICAL CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)

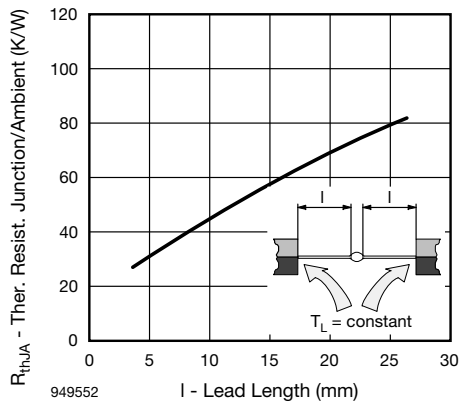


Fig. 1 - Max. Thermal Resistance vs. Lead Length

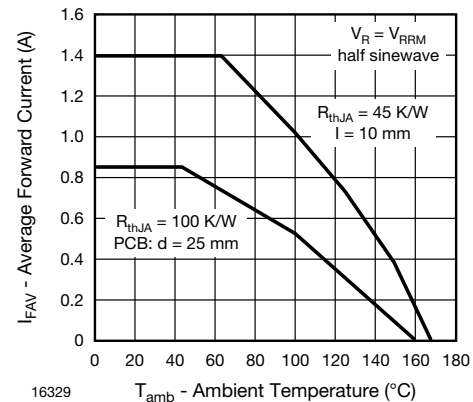


Fig. 3 - Max. Average Forward Current vs. Ambient Temperature

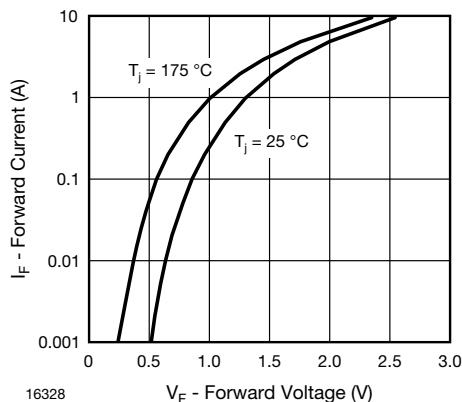


Fig. 2 - Max. Forward Current vs. Forward Voltage

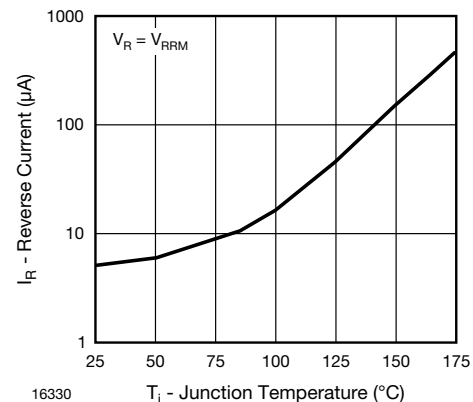


Fig. 4 - Max. Reverse Current vs. Junction Temperature

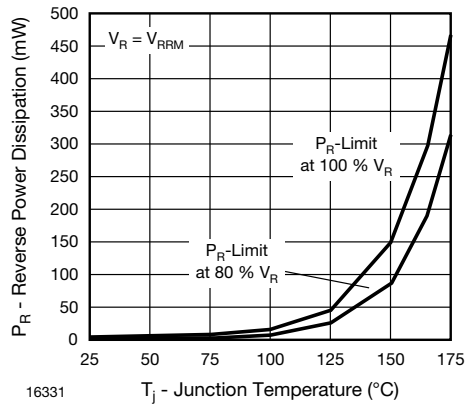


Fig. 5 - Max. Reverse Power Dissipation vs. Junction Temperature

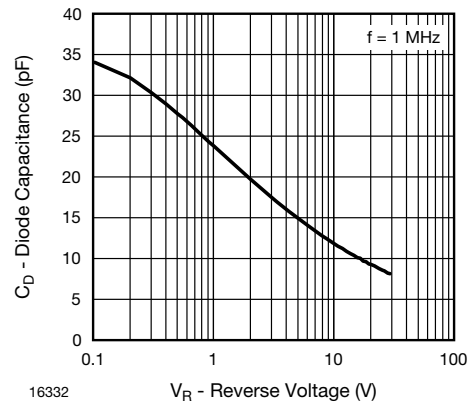
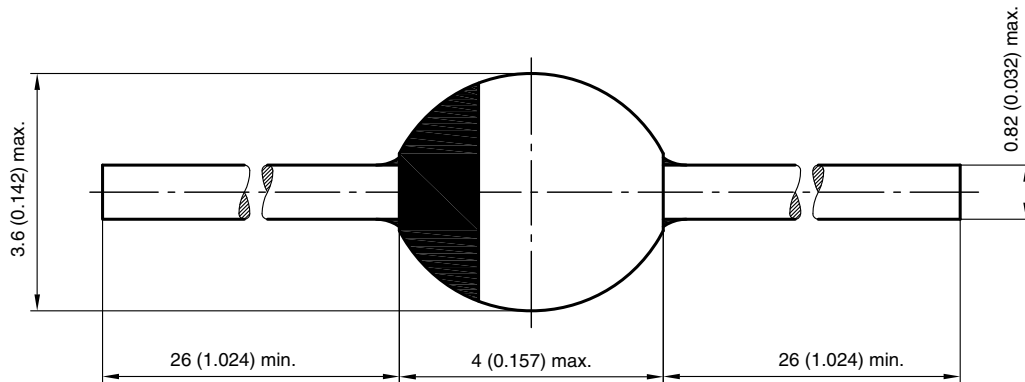


Fig. 6 - Diode Capacitance vs. Reverse Voltage

PACKAGE DIMENSIONS in millimeters (inches): **SOD-57**



20543
Rev. 3 - Date: 09.February 2005
Document no.:6.563-5006.3-4



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